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**Laffon de Mazieres et al.**

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(54) **ELECTRONIC DEVICE CABLE**

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(\*\*) Term: **14 Years**

(21) Appl. No.: **29/430,010**

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(51) **LOC (10) Cl.** ..... **14-02**

(52) **U.S. Cl.**  
USPC ..... **D14/433; D13/154**

(58) **Field of Classification Search**  
USPC ..... D13/147, 154, 153, 139, 156, 133, 108,  
D13/137.2, 139.7, 173; D14/317, 357, 432,  
D14/433, 434, 435.1, 507, 138 C, 356, 142,  
D14/144; 439/887, 352, 607, 502; 361/679  
CPC ..... H01R 31/06  
See application file for complete search history.

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(Continued)

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(74) *Attorney, Agent, or Firm* — Lee & Hayes, PLLC

(57) **CLAIM**

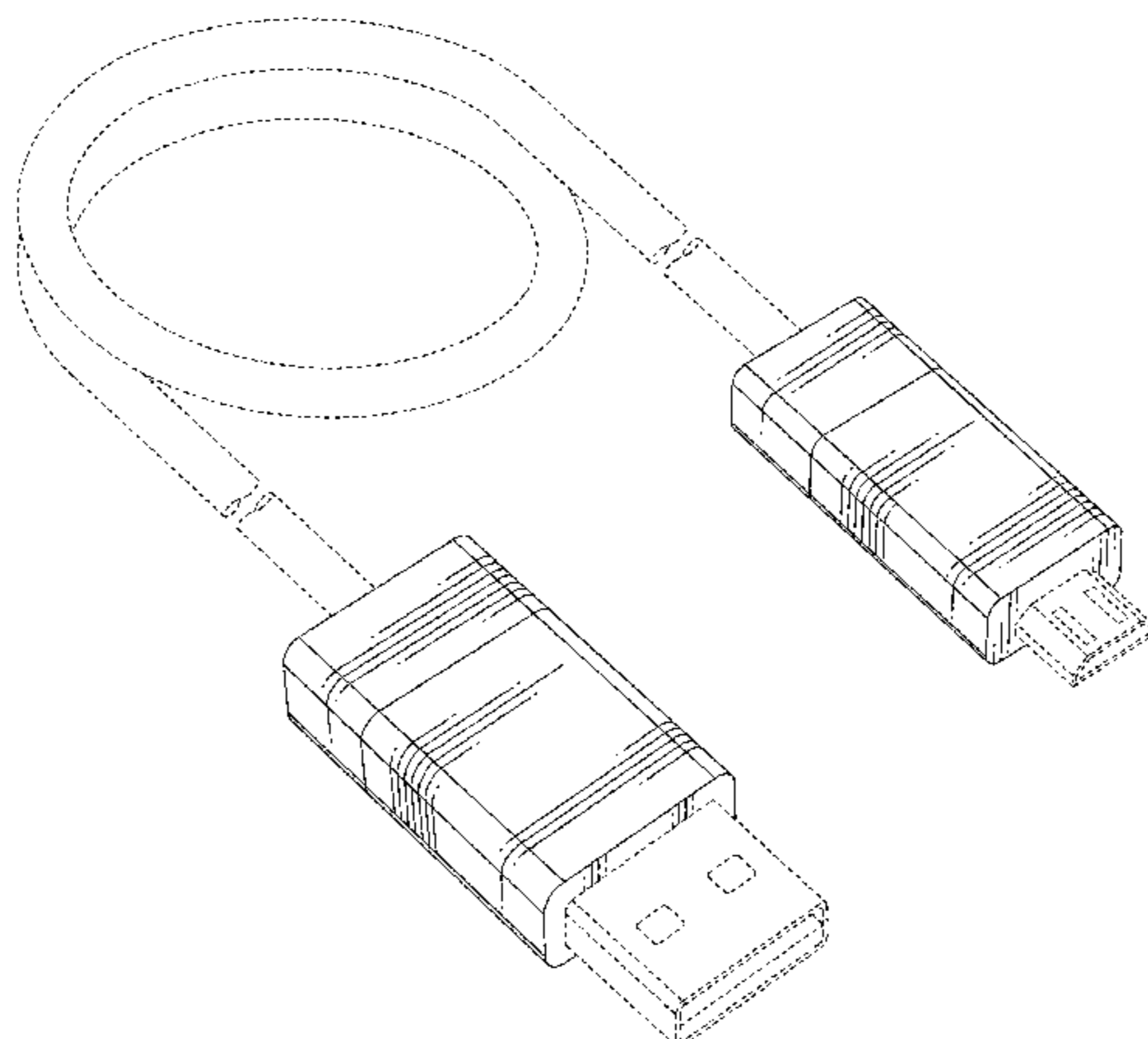
The ornamental design for an electronic device cable, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of an electronic device cable; FIG. 2 is another perspective view of the electronic device cable of FIG. 1; FIG. 3 is a top plan view of the electronic device cable of FIG. 1; FIG. 4 is a bottom plan view of the electronic device cable of FIG. 1; FIG. 5 is a back elevation view of the electronic device cable of FIG. 1; FIG. 6 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 6-6 in FIG. 5; FIG. 7 is a partial cross-sectional view of the electronic device cable of FIG. 1, taken along line 7-7 in FIG. 5; FIG. 8 is a front elevation view of the electronic device cable of FIG. 1; FIG. 9 is a left-side elevation view of the electronic device cable of FIG. 1; and, FIG. 10 is a right-side elevation view of the electronic device cable of FIG. 1.

The broken lines are directed to unclaimed portions and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



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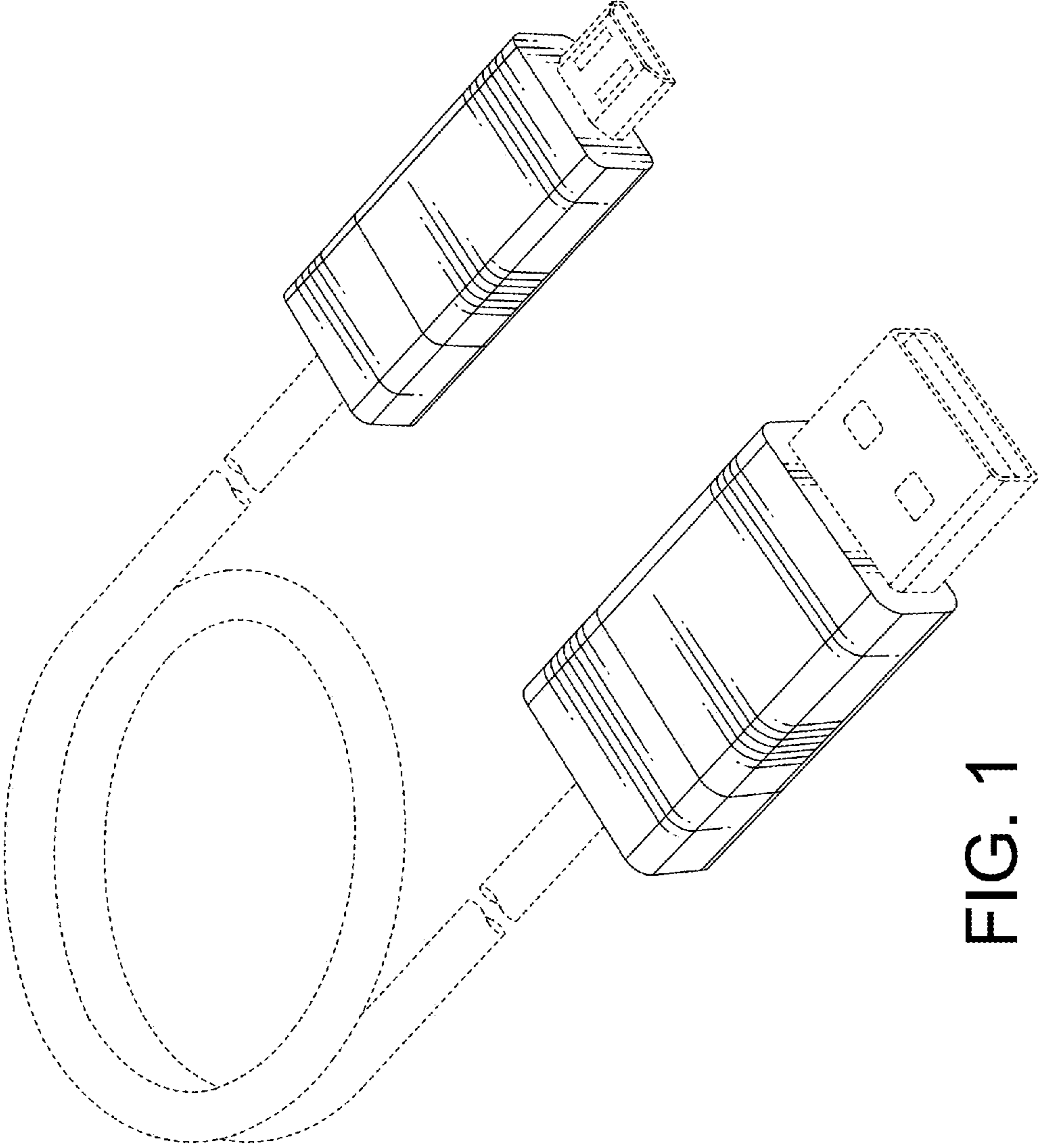


FIG. 1

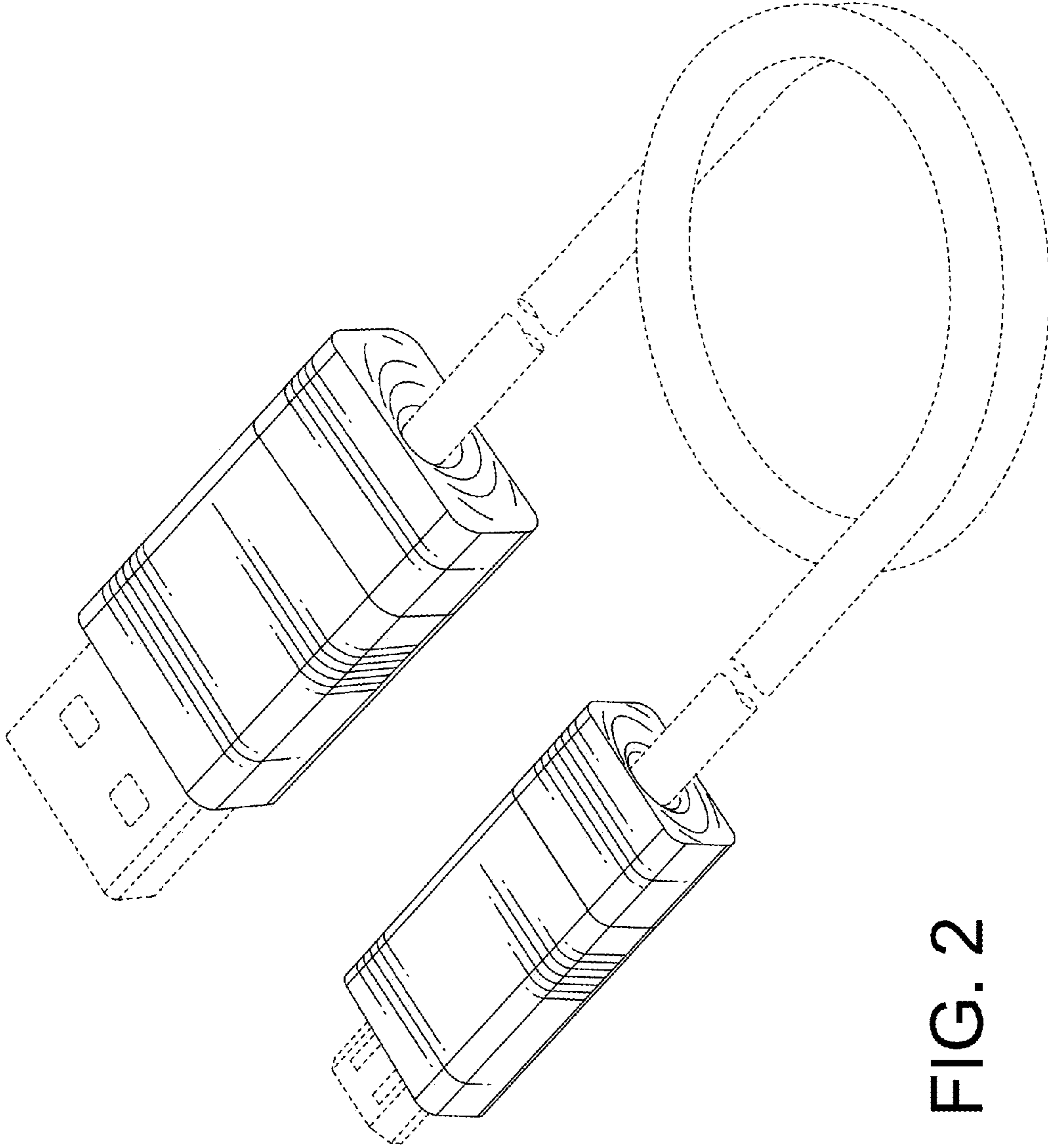


FIG. 2

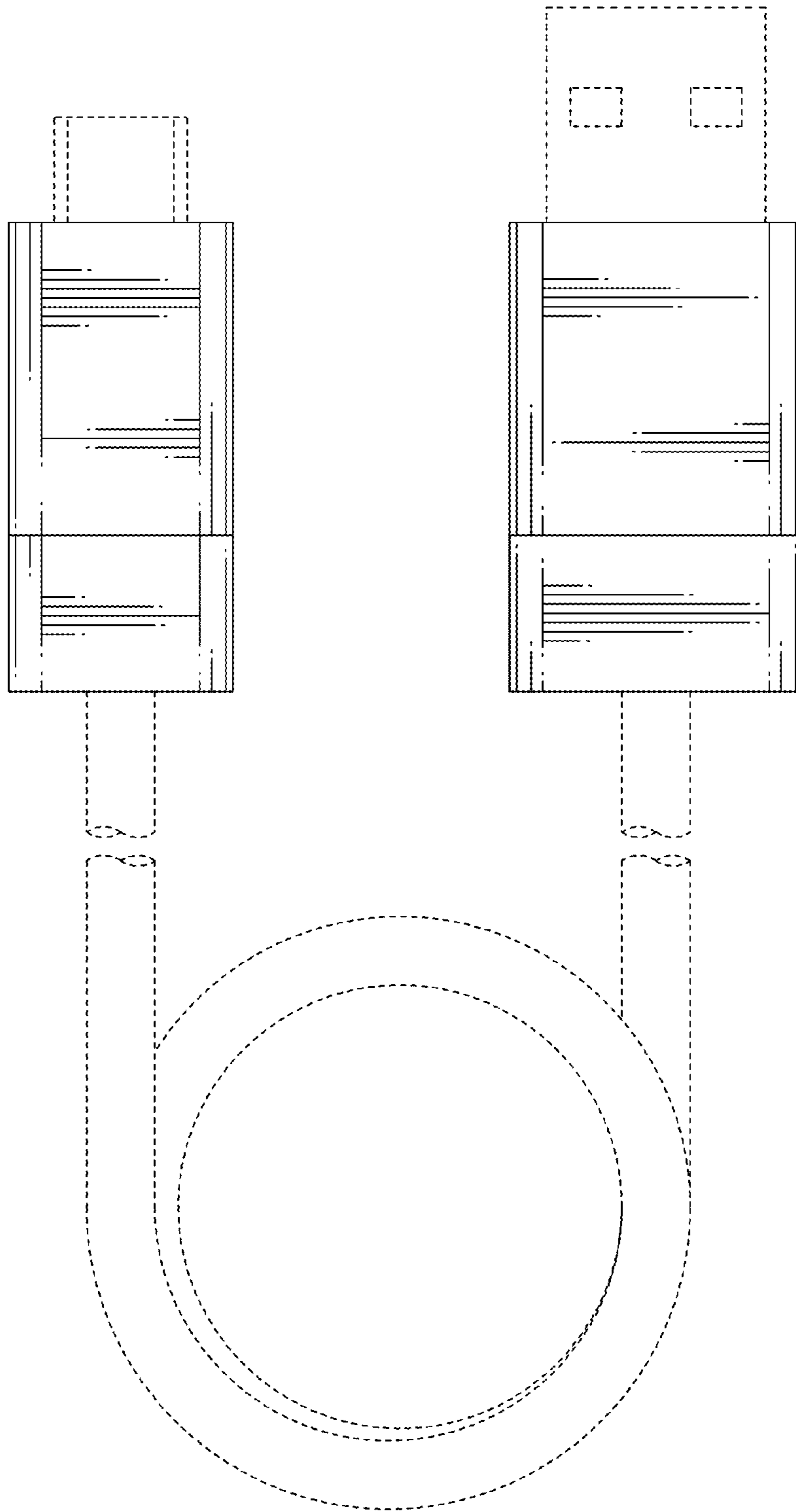


FIG. 3

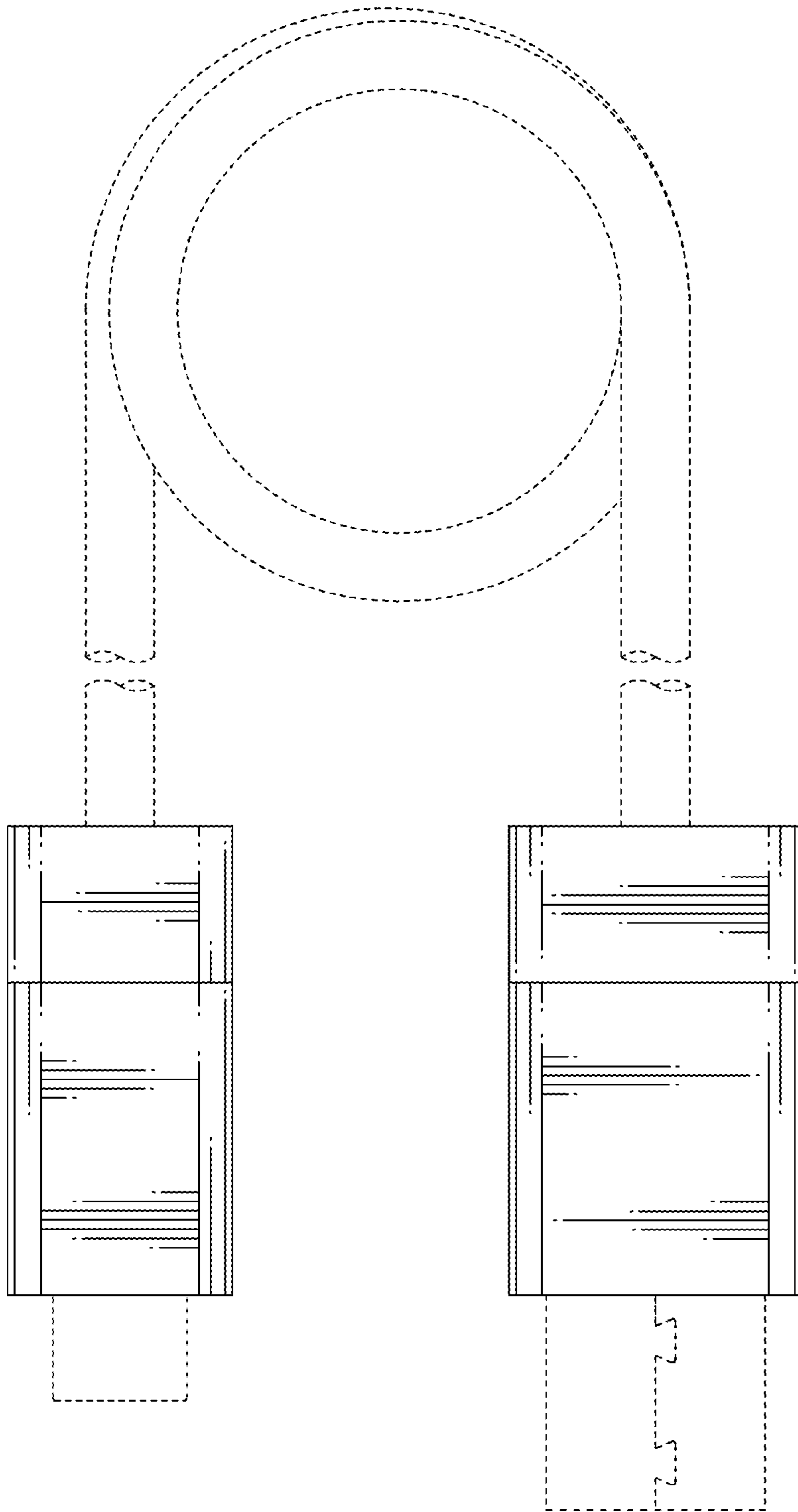


FIG. 4



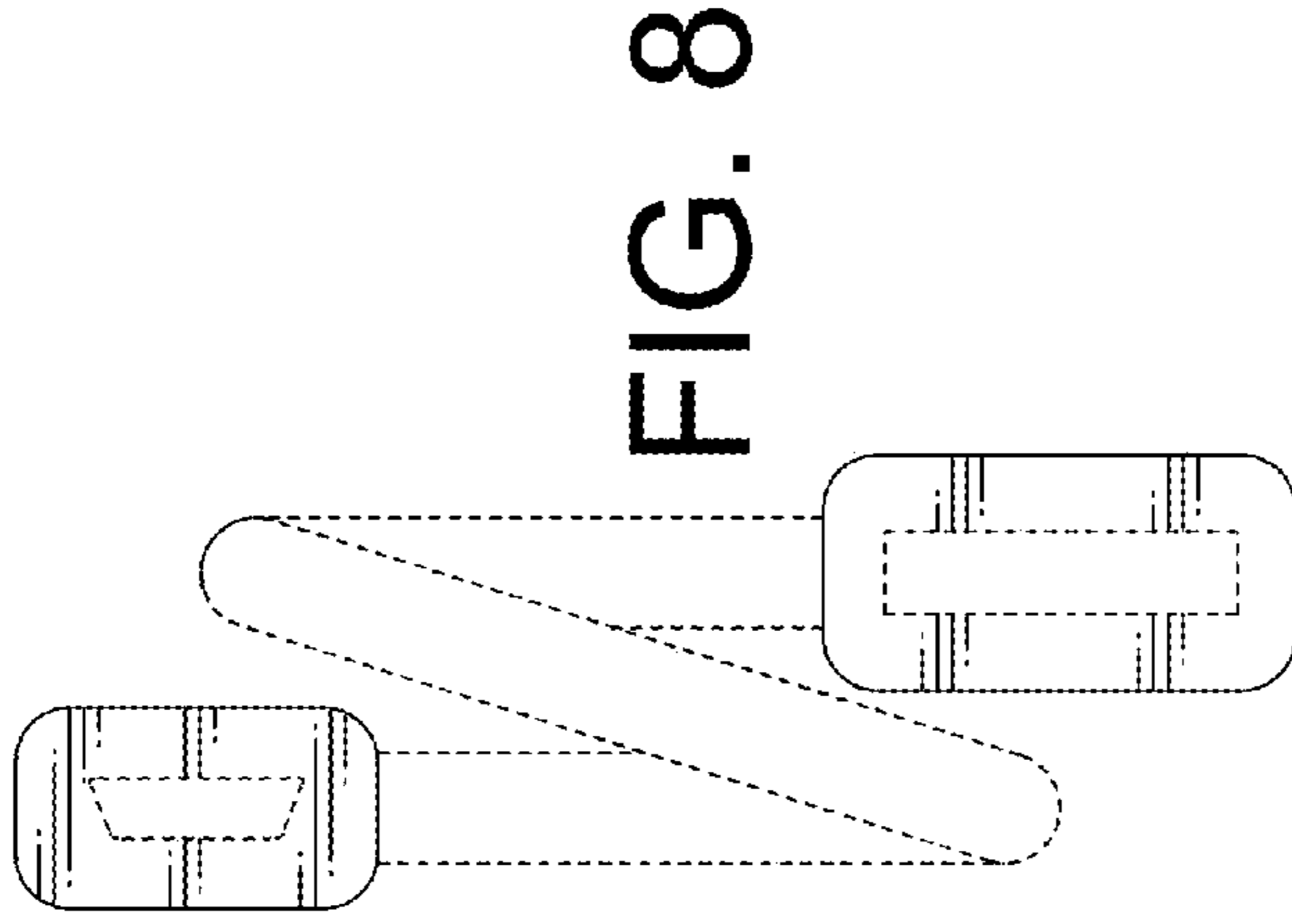


FIG. 8

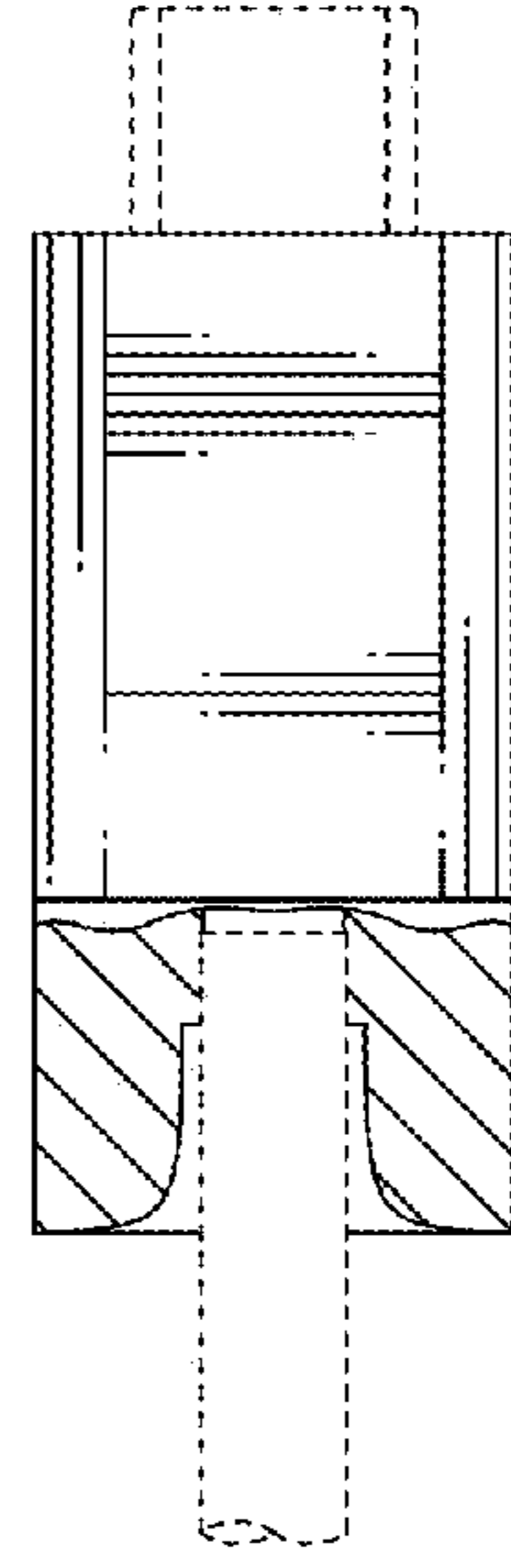


FIG. 7

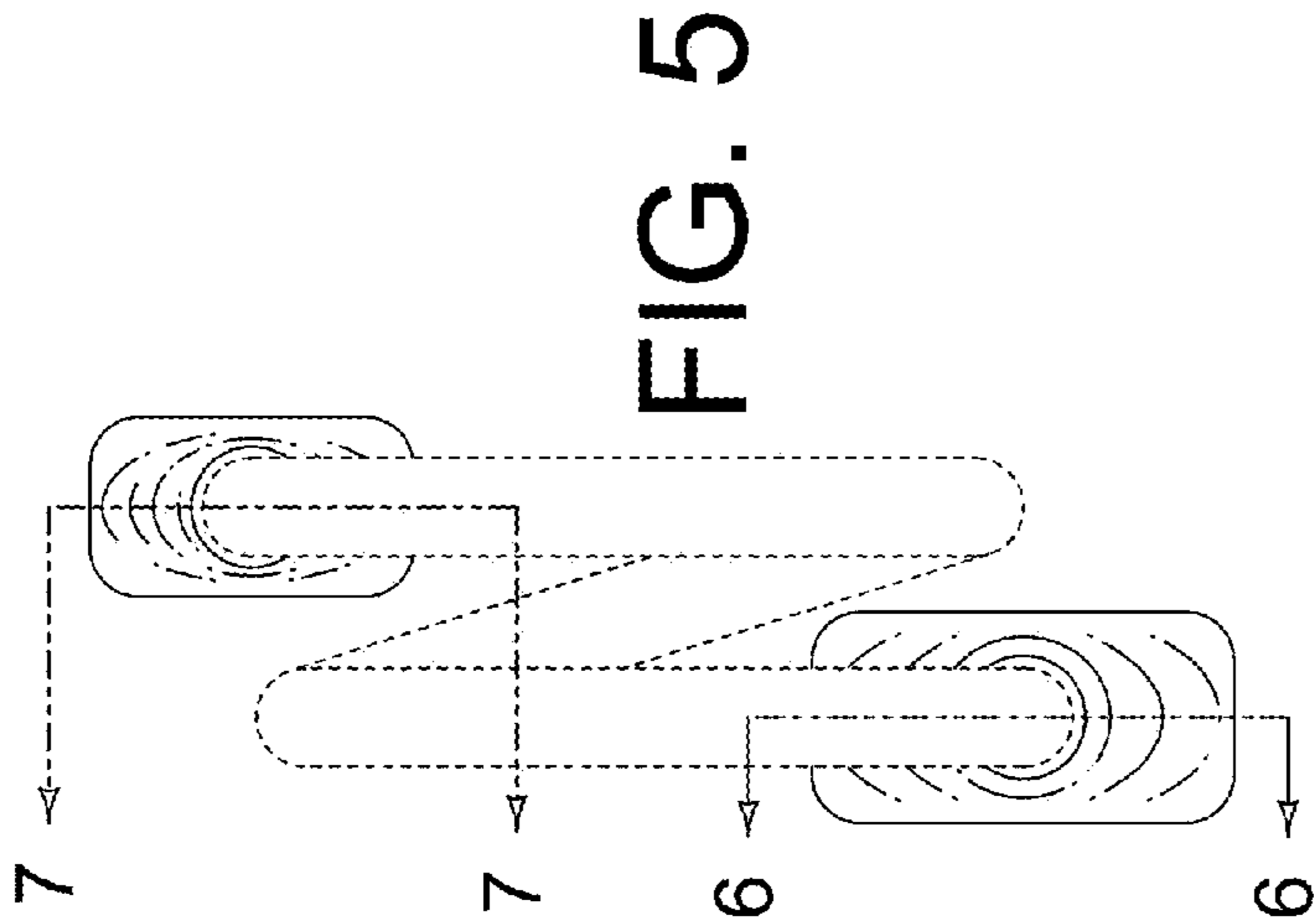


FIG. 5

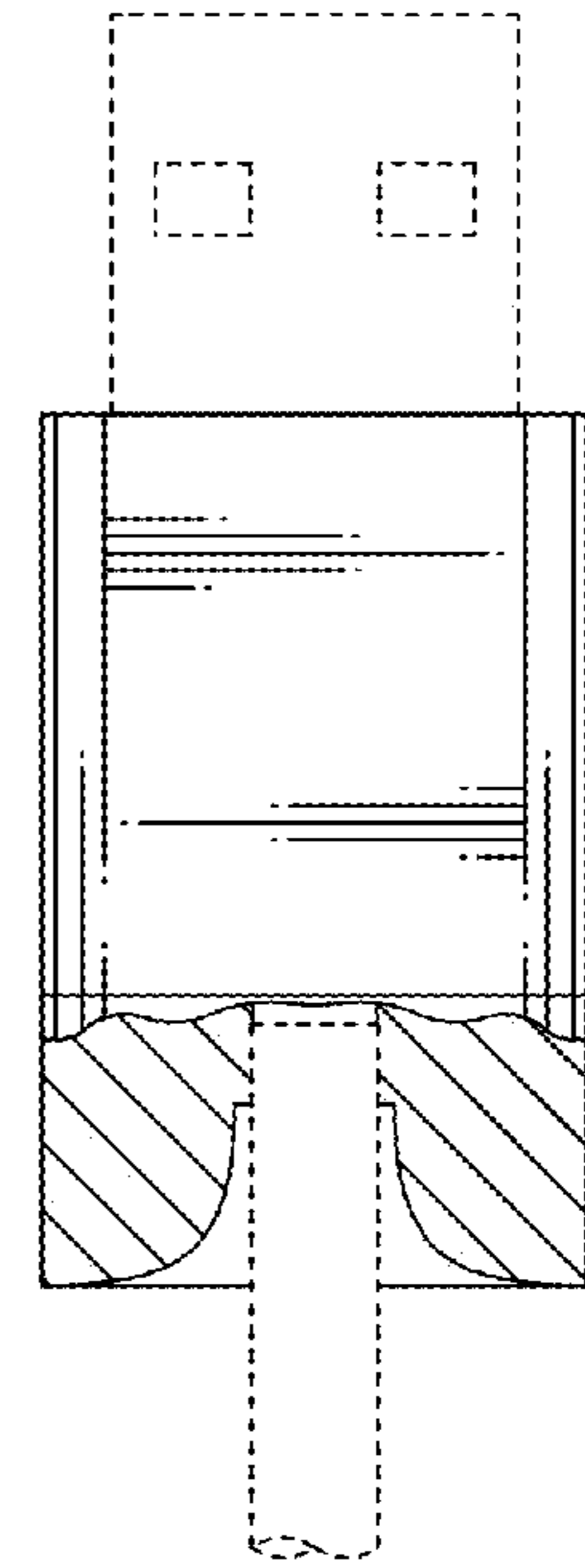


FIG. 6

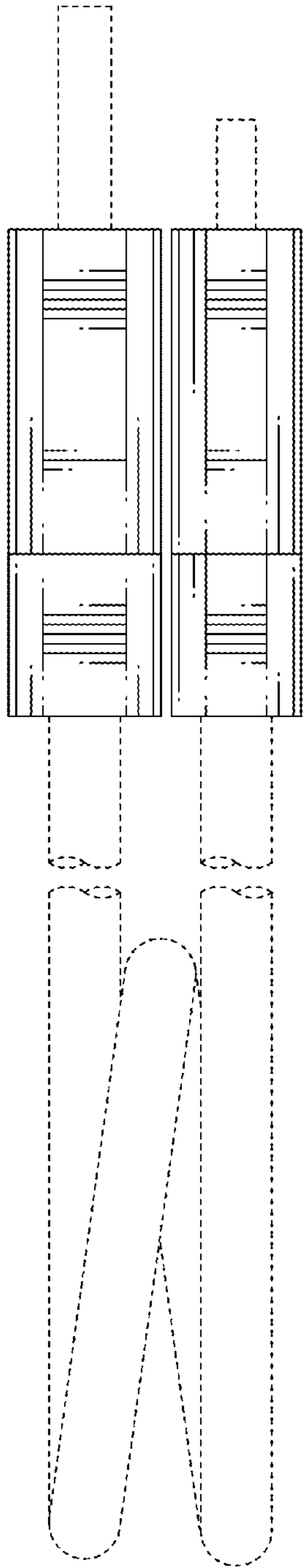


FIG. 9

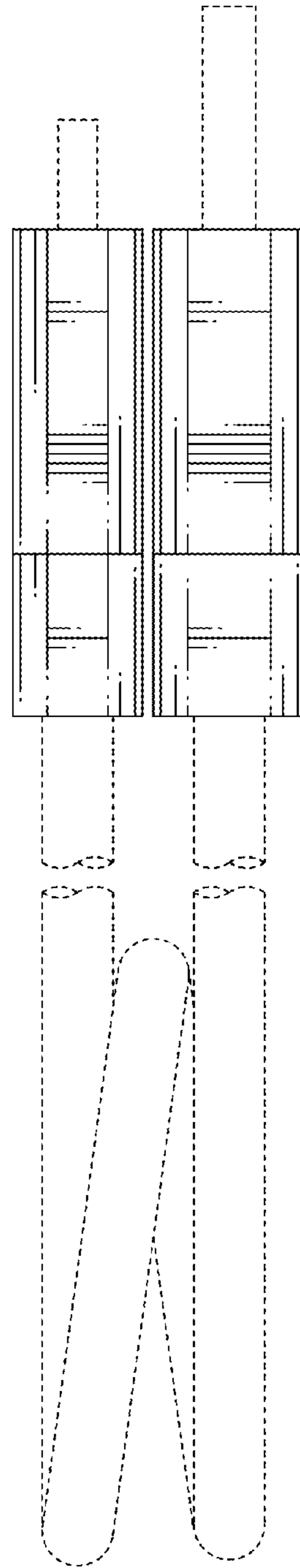


FIG. 10